

IN THE CLAIMS:

1. (Cancelled)

2. (Cancelled)

3. (Cancelled)

4. (Cancelled)

5. (Cancelled)

6. (Cancelled)

7. (Cancelled)

8. (Cancelled)

9. (Cancelled)

10. (Cancelled)

11. (Cancelled)

12. (Cancelled)

13. (Cancelled)

14. (Cancelled)

15. (Currently Amended) A method of storing a plurality of wafers in a stack within a wafer storage container, the method comprising the steps of:

placing each of a plurality of wafers wafer on one of a corresponding plurality of wafer frames frame to obtain a plurality of wafer assemblies, each wafer frame including at least one alignment artifact disposed thereon, the step of placing resulting in adhesion between each wafer and corresponding wafer frame sufficient to prevent substantial movement of the wafer relative to the corresponding wafer frame;

sequentially placing each wafer assembly into a wafer storage chamber to form a stack wherein each wafer element has a known orientation that is visible when the chamber is uncovered, the step of sequentially placing including the step of aligning engagement of the at least one alignment artifact disposed on each wafer frame with at least one orientation artifact disposed within the wafer storage container, thereby orienting each wafer frame in the wafer storage container and preventing substantial rotational movement of the each wafer frame and the wafer disposed thereon within the storage chamber; and

covering the wafer storage chamber with a cover to fully enclose the stack.

16. (Currently Amended) The method ~~according to~~ of claim 15 wherein the step of placing ~~includes~~ comprises placing an adhesive film over an open area of each wafer frame.

17. (Currently Amended) The method ~~according to~~ of claim 15 wherein the step of placing further ~~includes~~ comprises the step of placing each wafer on the adhesive film.

18. (Currently Amended) A ~~The~~ method ~~according to~~ of claim 15 wherein the step of sequentially placing each wafer assembly into the wafer storage chamber to form the stack ~~includes~~ comprises aligning a plurality of alignment artifacts

disposed on each wafer frame with a corresponding plurality of orientation artifacts disposed within the wafer storage chamber.

19. (New) A method of storing a stack of wafers in a wafer storage container, the method comprising the steps of:

providing a plurality of wafer elements, each wafer element having at least one alignment artifact;

providing a container that conforms to the outer dimension of the wafer elements, wherein the container includes at least one orientation artifact that is capable of engagement with an alignment artifact of each wafer element;

placing the wafer elements in the container so that the alignment artifact of each wafer element mates with at least one orientation artifact of the container.

20. (New) The method of storing a wafer stack in the wafer storage container of claim 19, wherein each wafer element has an orientation that is visible when the chamber is uncovered.

21. (New) The method of storing a wafer stack in the wafer storage container of claim 19, wherein each wafer element has a known orientation that is visible when the chamber is uncovered.

22. (New) The method of claim 19 wherein the step of placing the wafer elements into the wafer storage chamber comprises aligning a plurality of alignment artifacts disposed on each wafer frame with a corresponding plurality of orientation artifacts disposed within the wafer storage chamber.